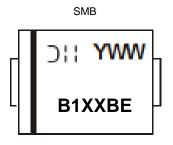


Marking Information (continued)



B1XXBE = Product Type Marking Code, ex: B150BE DII = Manufacturers' Marking YWW = Date Code Marking Y = Last Digit of Year (ex: 0 for 2020) WW = Week Code (01 to 53)

Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	B150AE B150BE	B160AE B160BE	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	Vrrm V _{rwm} Vrm	50	60	V
Average Rectified Output Current	lo	1		A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	3	0	А

Thermal Characteristics

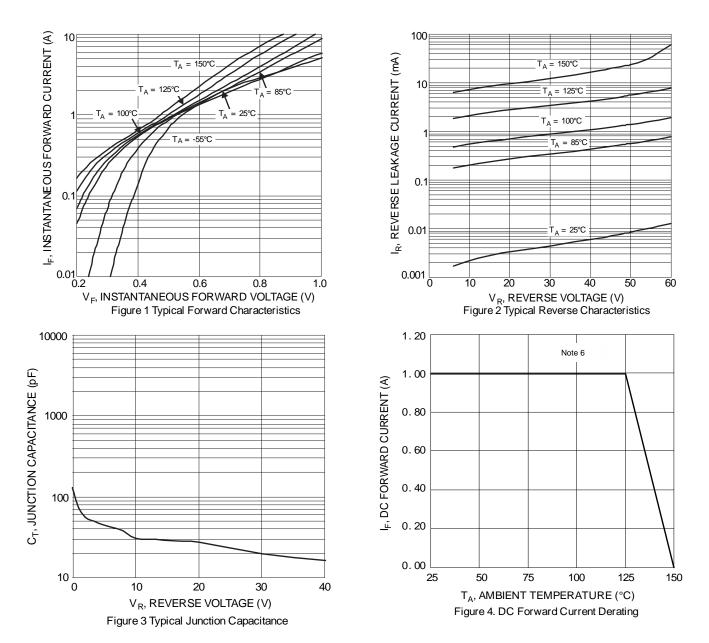
Characteristic		Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 6)	SMA SMB	Reja	95 90	°C/W
Typical Thermal Resistance Junction to Case (Note 6)	SMA SMB	Rejc	45 40	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Valtage Drep	VF		_	0.65	N/	I _F = 1A, T _J = +25°C
Forward Voltage Drop	VF	—	—	—	v	IF = 1A, TJ = +125°C
B150AE/B150BE		_	_	0.1		$V_{R} = 50V, T_{J} = +25^{\circ}C$
Leakage Current (Note 7) B160AE/B160BE	IR	—	—	0.2	mA	V _R = 60V, T _J = +25°C
		—	8.0	—		$V_R = 60V, T_J = +125^{\circ}C$
Typical Capacitance	Ст		45		pF	$V_R = 4.0V$, f = 1MHz

Notes: 6. Device mounted on FR-4 substrate, 0.4" × 0.5", 2oz, single-sided, PC boards with 0.2" × 0.25" copper pad. 7. Short duration pulse test used to minimize self-heating effect.



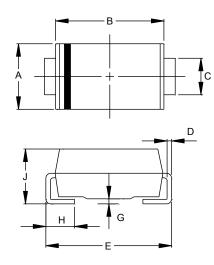




Package Outline Dimensions

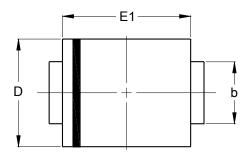
Please see http://www.diodes.com/package-outlines.html for the latest version.

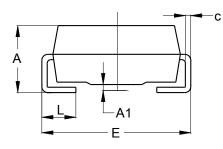
(1) Package Type: SMA



SMA			
Dim	Min	Max	
Α	2.29	2.92	
В	4.00	4.60	
С	1.27	1.63	
D	0.15	0.31	
E	4.80	5.59	
G	0.05	0.20	
Н	0.76	1.52	
J	1.96	2.40	
All Dimensions in mm			

(2) Package Type: SMB





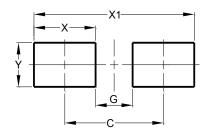
SMB				
Dim	Min	Max		
Α	2.00	2.50		
A1	0.05	0.20		
b	1.96	2.21		
С	0.15	0.31		
D	3.30	3.94		
Е	5.00	5.59		
E1	4.06	4.57		
L	0.76	1.52		
All Dimensions in mm				



Suggested Pad Layout

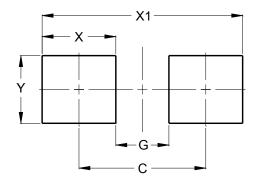
Please see http://www.diodes.com/package-outlines.html for the latest version.

(1) Package Type: SMA



Dimensions	Value (in mm)
С	4.00
G	1.50
Х	2.50
X1	6.50
Y	1.70

(2) Package Type: SMB



Dimensions	Value (in mm)
С	4.30
G	1.80
Х	2.50
X1	6.80
Y	2.30



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